

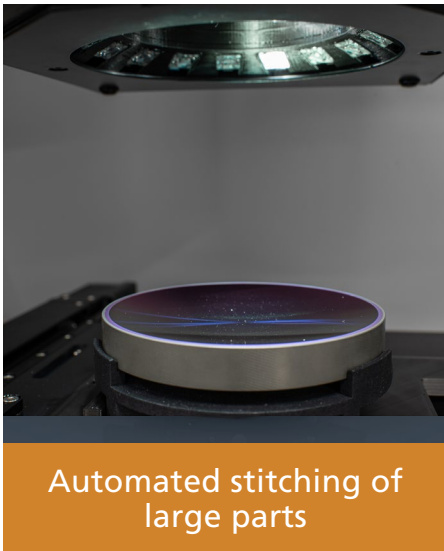
ARGOS matrix 200

automated scratch-dig inspection

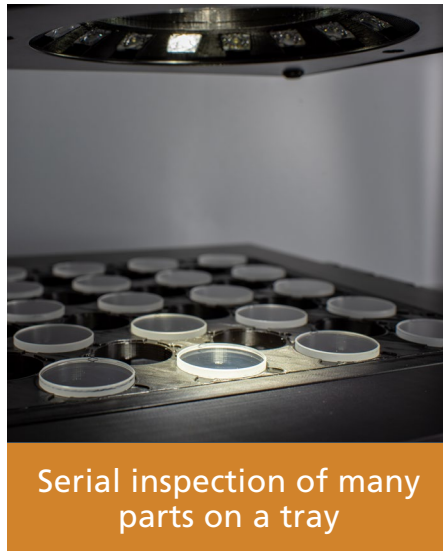
DIOPHTIC
thinking your optics



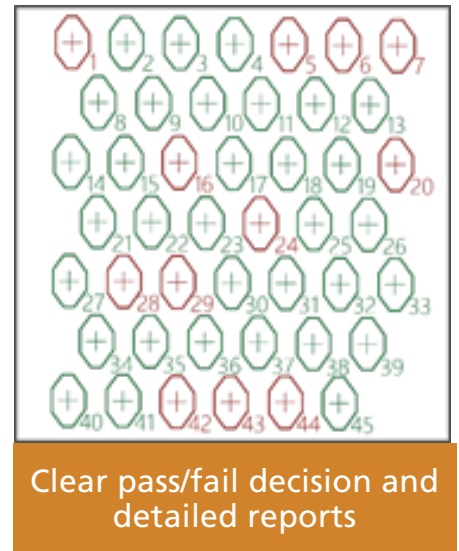
- FULLY AUTOMATED SURFACE INSPECTION
- VERSATILE FROM MICRO-OPTICS TO WAFERS
- OBJECTIVE AND REPRODUCIBLE



Automated stitching of large parts



Serial inspection of many parts on a tray



Clear pass/fail decision and detailed reports

BENEFITS

Large flexibility: any shape from aspheric micro lenses to 8" wafers can be inspected.

Automated serial inspection without user interaction reduces cost and improves process quality.

Objective test results with clear decisions and detailed information on relevant defects and statistics.

FUNCTIONALITY

ARGOS matrix 200 is equipped with a high-resolution camera and a switchable dark-field illumination. Images with different lighting configurations are fused for reliable defect detection with high repeatability. A precision 8" stage

allows inspection of large numbers of parts in a tray. Our stitching mode allows inspection of large parts - flat or curved. PDF test reports with clear decision and detailed information are automatically created.

SPECIFICATIONS

| Parameter | ARGOS matrix 200 |
|--|--|
| Nominal resolution (object-side pixel pitch) | 2.5 µm |
| Maximum inspection area | 205 × 205 mm |
| Smallest ISO 10110-7 specification | 5/1 × 0.016, L1 × 0.0063, E0.025 |
| Smallest visible defects* | < 1 µm |
| Precision of size measurement* | < 1.5 µm |
| Surface material | glass, metal, semiconductors, plastics |
| Inspection duration | 7 min for 8" wafer |
| System size | ca. 700 × 600 × 600 mm |

*for details see technical specification document